

**Amendments to the Claims:**

This Listing of Claims will replace all prior versions and listings of claims in the application:

**Listing of Claims:**

Claims 1-17 (canceled).

18. (currently amended) A method as in ~~claim 17~~claim 24 wherein step (b) advances curing of the thermosetting resin.

19. (currently amended) A method as in ~~claim 17~~claim 24 wherein the second temperature is between about 220°C and about 260°C.

20. (currently amended) A method as in ~~claim 17~~claim 24 further comprising a step of inspecting the semiconductor device.

21. (currently amended) A method as in ~~claim 17~~claim 24 wherein the semiconductor device comprises an integrated circuit.

22. (currently amended) A method as in ~~claim 17~~claim 24 wherein step (a) includes a transfer molding process.

23. (currently amended) A method as in ~~claim 17~~claim 24 wherein step (a) includes a potting process.

24. (previously presented) A method of making a semiconductor device comprising:

(a) sealing the semiconductor device in a package by surrounding it with thermosetting resin and thermally curing the resin at a first temperature;

(b) baking the thermosetting resin at a second temperature not higher than the first temperature; and

- (c) further baking the thermosetting resin at a third temperature higher than the first temperature; and
- (d) inspecting the semiconductor device.

25. (previously presented) A method as in claim 24 wherein a conductive lead is adhesively affixed to a main surface of the semiconductor device.

26. (previously presented) A method as in claim 25 wherein the conductive lead is adhesively affixed to a peripheral portion of the main surface of the semiconductor device.

27. (previously presented) A method as in claim 26 wherein an electrode of the semiconductor device is electrically connected to the conductive lead.

Claims 28-30 (canceled).